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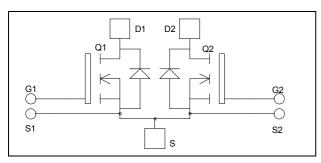
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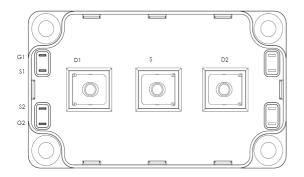
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Dual common source MOSFET Power Module





Absolute maximum ratings

$\begin{vmatrix} V_{DSS} = 1200V \\ R_{DSon} = 150m\Omega \text{ typ } @ \text{ Tj} = 25^{\circ}C \\ I_{D} = 60A @ \text{ Tc} = 25^{\circ}C \end{vmatrix}$

Application

- AC Switches
- Switched Mode Power Supplies
- Uninterruptible Power Supplies

Features

- Power MOS 7[®] MOSFETs
 - Low R_{DSon}
 - Low input and Miller capacitance
 - Low gate charge
 - Avalanche energy rated
 - Very rugged
- Kelvin source for easy drive
 - Very low stray inductance
 - Symmetrical design
 - M5 power connectors
- High level of integration

Benefits

- Outstanding performance at high frequency operation
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Low profile
- RoHS Compliant

Symbol Max ratings Unit Parameter V_{DSS} Drain - Source Breakdown Voltage 1200 V $T_c = 25^{\circ}C$ 60 Continuous Drain Current I_D $T_c = 80^{\circ}C$ 45 А I_{DM} Pulsed Drain current 240 Gate - Source Voltage V V_{GS} ± 30 R_{DSon} Drain - Source ON Resistance 175 mΩ Maximum Power Dissipation $T_c = 25^{\circ}C$ 1250 W P_{D} Avalanche current (repetitive and non repetitive) 22 А I_{AR} EAR Repetitive Avalanche Energy 50 mJ Single Pulse Avalanche Energy 3000 EAS

CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on www.microsemi.com



All ratings (a) $T_j = 25^{\circ}C$ unless otherwise specified

Electrical Characteristics

Symbol	Characteristic	Test Conditions		Min	Тур	Max	Unit	
I _{DSS}	Zero Gate Voltage Drain Current	$V_{GS} = 0V, V_{DS} = 1200V$	$T_j = 25^{\circ}C$			500		
	Zero Gate voltage Drain Current	$V_{GS} = 0V, V_{DS} = 1000V$	$T_j = 125^{\circ}C$			3000	μA	
R _{DS(on)}	Drain – Source on Resistance	$V_{GS} = 10V, I_D = 30A$			150	175	mΩ	
V _{GS(th)}	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 10 \text{mA}$		3		5	V	
I _{GSS}	Gate – Source Leakage Current	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0 \text{ V}$	7			±250	nA	

Dynamic Characteristics

Symbol	Characteristic	Test Conditions	Min	Тур	Max	Unit	
C _{iss}	Input Capacitance	$V_{GS} = 0V$		20.6			
Coss	Output Capacitance	$V_{\rm DS} = 25 V$		3.08		nF	
C _{rss}	Reverse Transfer Capacitance	f = 1MHz		0.52			
Qg	Total gate Charge	$V_{GS} = 10V$		748		nC	
Q_{gs}	Gate – Source Charge	$V_{Bus} = 600 V$		96			
Q_{gd}	Gate – Drain Charge	$I_{\rm D} = 60 {\rm A}$		480			
T _{d(on)}	Turn-on Delay Time	Inductive switching @ 125°C $V_{GS} = 15V$ $V_{Bus} = 800V$ $I_D = 60A$ $R_G = 1.2\Omega$		20			
T _r	Rise Time			15		ns	
T _{d(off)}	Turn-off Delay Time			160			
T _f	Fall Time			45			
Eon	Turn-on Switching Energy	Inductive switching @ 25°C		3.96			
$\mathrm{E}_{\mathrm{off}}$	Turn-off Switching Energy			2.74		mJ	
Eon	Turn-on Switching Energy	Inductive switching @ 125°C $V_{GS} = 15V$, $V_{Bus} = 800V$ $I_D = 60A$, $R_G = 1.2\Omega$		6.26			
$\mathrm{E}_{\mathrm{off}}$	Turn-off Switching Energy			3.43		mJ	

Source - Drain diode ratings and characteristics

Symbol	Characteristic	Test Conditions		Min	Тур	Max	Unit
Is	Continuous Source current		$Tc = 25^{\circ}C$			60	٨
	(Body diode)		$Tc = 80^{\circ}C$			45	A
V _{SD}	Diode Forward Voltage	$V_{GS} = 0V, I_S = -60A$				1.3	V
dv/dt	Peak Diode Recovery 1					10	V/ns
t _{rr}	Reverse Recovery Time	$I_{\rm S} = -60 {\rm A}, {\rm V}_{\rm R} = 600 {\rm V}$			1291		ns
Q _{rr}	Reverse Recovery Charge	$di_{S}/dt = 400A/\mu s$			116		μC

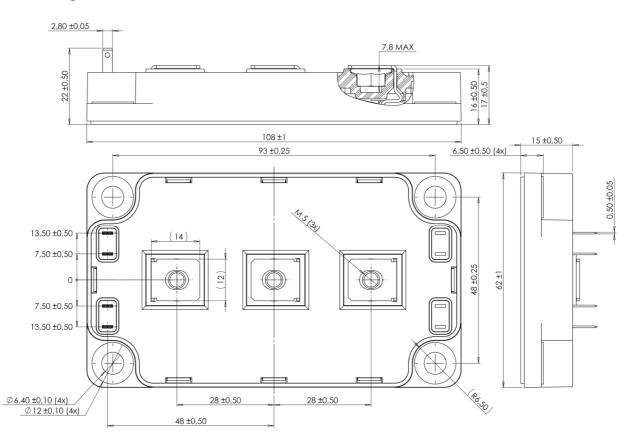
• dv/dt numbers reflect the limitations of the circuit rather than the device itself. $I_S \le -60A$ di/dt $\le 700A/\mu s$ $V_R \le V_{DSS}$ $T_i \le 150^{\circ}C$



Thermal and package characteristics

Symbol	Characteristic			Min	Тур	Max	Unit
R _{thJC}	Junction to Case Thermal Resistance					0.1	°C/W
V _{ISOL}	RMS Isolation Voltage, any terminal to case t =1 min, 50/60Hz			4000			V
T _J	Operating junction temperature range			-40 150			
T _{STG}	Storage Temperature Range			-40		125	°C
T _C	Operating Case Temperature			-40		100	
Torque	Mounting torque	To heatsink	M6	3		5	N.m
	would be determined and the second se	For terminals	M5	2		3.5	19.111
Wt	Package Weight					300	g

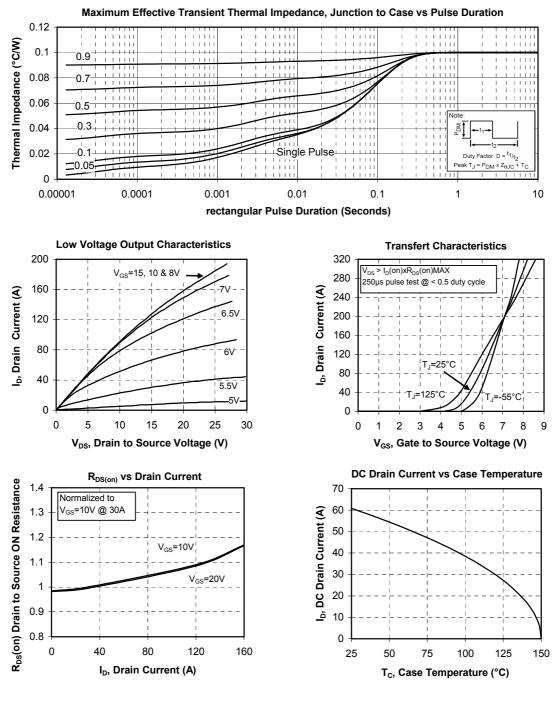
SP6 Package outline (dimensions in mm)



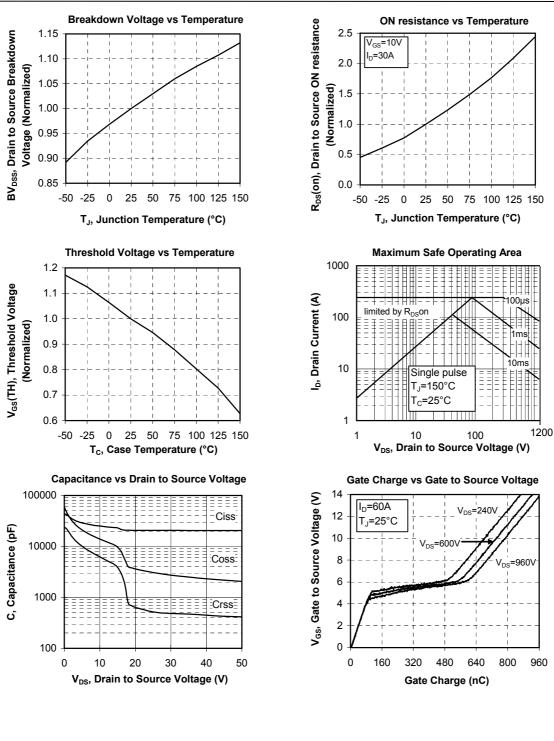
See application note APT0601 - Mounting Instructions for SP6 Power Modules on www.microsemi.com



Typical Performance Curve

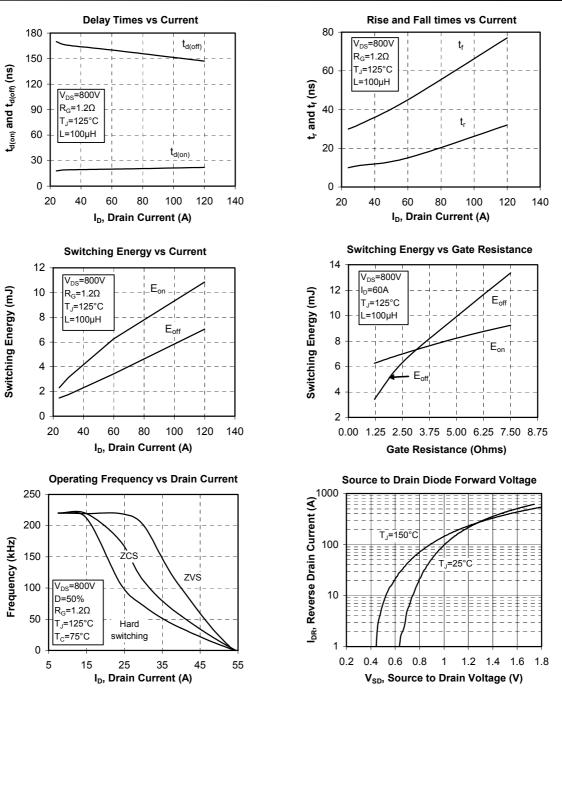






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